Sherlock User Forums

To better accommodate the users of our Sherlock Automated DesignAnalysis™ software, we have developed a User Forum which will provide insight in FAQs, discussions on Sherlock releases, feature requests, and tips and tricks. There will also be a place for users to input their own experiences.

Please go to Sherlock User Forum. Once you enter your Sherlock account information you will receive a confirmation and you will be directed to the Forum.

Meet the DfR Folks!!

Greg Caswell is an industry renowned expert in the fields of SMT, advanced packaging, printed board fabrication, circuit card assembly, and bonding solutions using nanotechnology.

He has been well-regarded as a leader in the electronics contract manufacturing and component packaging industries for the past 40 years. His previous appointments include Vice President of Business Development for Newport Enterprises, Director of Engineering for VirTex Assembly Services, and Technical Director at Silicon Hills Design. Prior to joining DfR, Greg was the Vice President of Engineering at Reactive Nanotechnology (RNT). Greg continues to be the leading expert in NanoBonding®
implementation for component mounting applications. He has a B.S., in Electrical Engineering from Rutgers University and a B.A., Management from St. Edwards University. Here’s Greg.

Copper Wire Bonding – All the Rage!!

Wire bonding a die to a package has traditionally been performed using either aluminum or gold wire. The use of copper wire for ball-stitch bonding has been proposed and recently implemented in high volume to solve the cost issues with gold. As one would expect, bonding with copper is not as forgiving as with gold mainly due to oxide growth and hardness differences. This paper examines the common failure mechanisms that one might experience when implementing this new technology. For more information please contact Randy Schueller.

Extreme Drop Testing.

Using a special thermal management PCB design and a temperature controlled drop tower arrangement; DfR Solutions developed a process for evaluating the effects of mechanical shocks from drop testing at extreme temperatures. This white paper provides insight into this methodology. For more information, please contact Melissa Keener.

More articles of interest:

Know reliability, no counterfeits.

Unless you have been lucky enough to be on vacation in the Sahara Desert for the last 15 years, you have probably heard or been affected by counterfeit electronic parts (and, if you’ve been in the desert that long, you probably have other things to be worried about). However, with all the headlines, presentations, courses, articles, and case studies, the basics of counterfeiting can become slightly opaque.

The very first step in understanding counterfeiting is to understand the fundamental reason why counterfeiting survives and even thrives in this day and age. And the answer can be identified through the classic root-cause technique of the 5 Whys (ask why five times and you’ll get your answer).
Read more of Craig Hillman’s regular column in Global SMT & Packaging on Page 4 of the March issue.

The RoHS recast – Why medical OEMs need to get on their marks now

This article hits the nail on the head. Medical OEMs need to get started now, if they have not already, in transitioning their products to RoHS and Pb-free configurations.

DfR has been helping companies for several years to successfully manage this transition. Let us help you. For more information please contact Randy Schueller.

Automotive Warranty Report

Automotive manufacturers increase quality and decrease warranty costs to lowest levels of the decade. Read more in a recent Automotive Warranty Report. To learn how DfR Solutions helps automotive companies and their suppliers improve their product reliability, contact Jim McLeish.